

ThinFlex Corporation

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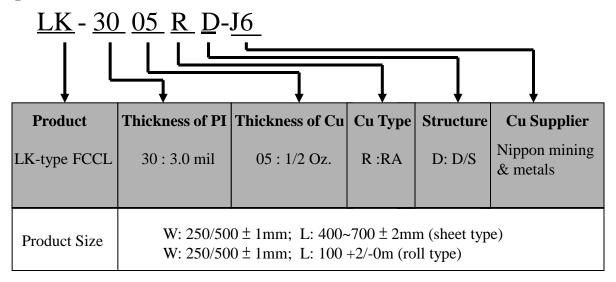
ThinFlex-LK, LK-3005RD-J6 Adhesiveless Double Sided Copper Clad Laminate

ThinFlex-LK, LK-3005RD-J6 is an adhesiveless double-sided (D/S) copper clad laminate via the laminating of ThinFlex-LK film with RA copper foil on both sides. The LK-3005RD-J6 adhesiveless composites are designed for a wide variety of flexible circuit applications which require advanced material performance, temperature resistance, fine pitch, high reliability, low dielectric constant and low dissipation factor.

1. Product Characteristics:

- * Excellent dimensional stability
- * Excellent flexibility
- * Excellent flammability and chemical resistance
- * Excellent thermal, mechanical, and electrical properties
- * Excellent etching capability
- * Low moisture absorption
- * Low dielectric constant and low dissipation factor

2. Specifications:



* Other product size is also available on customer's demand.

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3. Construction:

Copper foil Polyimide film

Copper foil

4. Properties:

Test item		Unit	LK-3005RD	-J6 Test Method
Peel Strength				
As Received		Kgf/cm	\ge 0.5	IPC-TM650 2.4.9
Solder Float		Kgf/cm	≧0.5	IPC-TM650 2.4.9
After Temp. Cycling		Kgf/cm	≧0.5	IPC-TM650 2.4.9
Chemical Resistance		Kgf/cm	≧0.5	IPC-TM650 2.3.2
Tensile Strength (Base Film)		Kg/mm²	≧ 15	IPC-TM-650 2.4.19
Elongation (Base Film)		%	≧ 15	IPC-TM-650 2.4.19
Tensile Modulus (Base Film)		Kg/mm²	≧ 400	ASTM D882
Initial Tear Strength (Base Film)		g	≥ 1000	IPC-TM-650 2.4.16
Propagation Tear Strength (Base Film)		g	≧ 18	IPC-TM-650 2.4.17.1
Flexural Endurance, MIT				
M.D.		Cycles	≧50	JIS-C 6471, 0.8mmR, 0.5kg
T.D.		Cycles	_ ≧50	JIS-C 6471, 0.8mmR, 0.5kg
Electrical Properties				
Surface Resistance		Ω	~10 ¹¹	IPC-TM650 2.5.17
Volume Resistance		Ω-cm	~1012	IPC-TM650 2.5.17
Insulation Resistance		Ω	~109	IPC-TM650 2.6.3.2
Dielectric Strength		kV/mil	5.0	ASTM-D149
Dielectric Constant		-	2.8	IPC-TM650 2.5.5.3
Dissipation factor		-	0.005	IPC-TM650 2.5.5.3
Physical and Thermal Pro	perties			
Dimensional Stability	M.D.	%	-0.2~ 0	IPC-TM650 2.2.4C
	T.D.	%	-0.2~ 0	IPC-TM650 2.2.4C
CTE		ppm/°C	28	ThinFlex
T _g		$^{\circ}\!\mathbb{C}$	320	ThinFlex
Solder Float	10sec at 288°C (550°F)	-	Pass	IPC-TM650 2.4.13
Moisture Absorption		%	1.0	IPC-TM650 2.6.2
Chemical Resistance		-	Pass	IPC-TM650 2.3.2
Thickness tolerance		um	111±10%	ThinFlex
UL Flame Class		-	VTM-0	UL94

^{*} Above data are typical values, and are not guaranteed values.

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5. Storage:

The shelf-life of LK-3005RD-J6 is at least 12 months for keeping at temperature of 25°C or less and relative humidity of 70% or less. By the way, it is no need to keep in the refrigeration and frozen condition.

Note: The information and data contained in this technical literature is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.

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